

Electronic Patent Application Fee Transmittal

Application Number:	10722288			
Filing Date:	25-Nov-2003			
Title of Invention:	THERMAL INTERFACE MATERIAL AND SOLDER PREFORMS			
First Named Inventor/Applicant Name:	Brian G. Lewis			
Filer:	Andrew C. Wegman/Valarie McLaurin			
Attorney Docket Number:	CEDA 7000.5			

Filed as Large Entity

Utility Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Claims in excess of 20	1202	31	50	1550
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Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Extension-of-Time:

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				1550